

## PROCESSOR AND IC SOCKETS

J

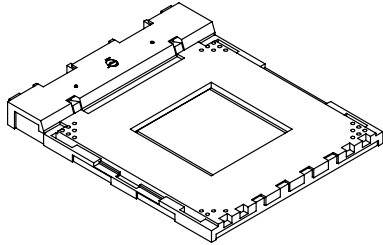
Micro PGA Sockets ..... J-2 to J-3

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## 1.27mm (.050") Pitch Micro PGA Socket

### 47387

**Key Version B  
Ball Grid Array (BGA)  
Solder Mount**



#### Features and Benefits

- Accepts Mobile Pentium® 4 and Mobile Celeron® Processor-M series
- Ball Grid Array (BGA) solder balls are self-centering and avoid the problem of bent tails
- LCP housing and cover with profile height of 3.30mm (.130")
- Dual-beam chamfered contact design provides low insertion force and good electrical performance
- Stainless steel cam retainer protects plastic cover from wear

#### Reference Information

Product Specification: PS-51248-020  
Packaging: Tray or tape on reel  
Designed In: Millimeters

#### Electrical

Voltage: 100V  
Current: 0.5A  
Contact Resistance: 25 milliohms max.  
Dielectric Withstanding Voltage: 360V AC  
Insulation Resistance: 800 Megohms min.

#### Mechanical

Durability: 50 cycles

#### Physical

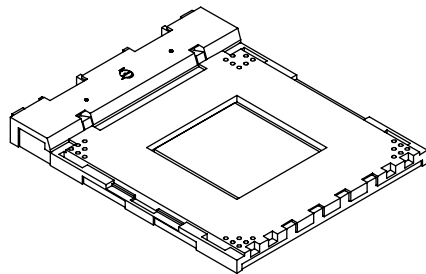
Housing: LCP, UL 94V-0  
Contact: Copper Alloy  
Plating: Contact Area—0.25µm (10µ") Gold  
Solder Tail Area—Tin/Silver/Copper  
Underplating: Nickel

Circuits	Order No.	Pick-and-Place Type	Packaging	Lead-free
478	<a href="#">47387-4781</a>	Pick-and-Place Cover	Tray	Yes
	<a href="#">47387-4782</a>	Mylar		
	<a href="#">47387-4783</a>	Pick-and-Place Cover	Tape on Reel	
	<a href="#">47387-4784</a>	Mylar		

## 1.27mm (.050") Pitch Micro PGA Socket

### 500210

**Key Version C  
Ball Grid Array (BGA)  
Solder Mount**



#### Features and Benefits

- Accepts Mobile Pentium® 4 and Mobile Celeron® Processor-M series
- Ball Grid Array (BGA) solder balls are self-centering and avoid the problem of bent tails
- LCP housing and cover with profile height of 3.30mm (.130")
- Dual-beam chamfered contact design provides low insertion force and good electrical performance
- Stainless steel cam retainer protects plastic cover from wear

#### Reference Information

Product Specification: PS-51248-005  
Packaging: Tray or tape on reel  
Designed In: Millimeters

#### Electrical

Voltage: 100V  
Current: 0.5A  
Contact Resistance: 25 milliohms max.  
Dielectric Withstanding Voltage: 360V AC  
Insulation Resistance: 800 Megohms min.

#### Mechanical

Durability: 50 cycles

#### Physical

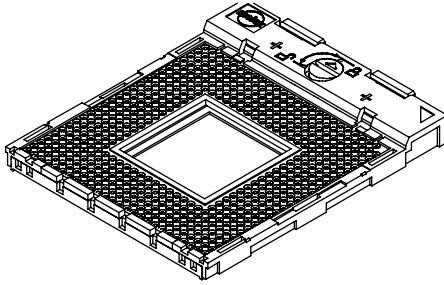
Housing: LCP, UL 94V-0  
Contact: Copper Alloy  
Plating: Contact Area—10µ" Gold  
Solder Tail Area—Tin/Silver/Copper  
Underplating: Nickel

Circuits	Order No.	Pick-and-Place Type	Packaging	Lead-free
478	<a href="#">500210-4785</a>	Mylar	Tape on Reel	Yes
	<a href="#">500210-4786</a>		Tray	
	<a href="#">500210-4787</a>	Pick-and-Place Cover	Tape on Reel	

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# 1.27mm (.050") Pitch Micro PGA Socket

**51248**  
**Ball Grid Array (BGA)**  
**Solder Mount**  
**479 Circuits**



### Features and Benefits

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- Dual-beam chamfered contact design provides low insertion force and good electrical performance
- Stainless steel cam retainer protects plastic cover from wear

### Reference Information

Product Specification: PS-51248-005 or PS-51248-020  
Packaging: Tape on reel  
Designed In: Millimeters

### Electrical

Voltage: 100V  
Current: 0.5A  
Contact Resistance: 25 milliohms max.  
Dielectric Withstanding Voltage: 360V AC  
Insulation Resistance: 800 Megohms min.

### Mechanical

Durability: 50 cycles

### Physical

Housing: LCP, UL 94V-0  
Contact: Copper Alloy  
Plating: Contact Area—10µ" Gold  
Solder Tail Area—Tin/Silver/Copper  
Underplating: Nickel

Circuits	Order No.	Pick-and-Place-Type	Packaging	Lead-free
479	<a href="#">51248-4799</a>	Pick-and-Place Cover	Tape on Reel	Yes

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